# 2SB0790 (2SB790)

### Silicon PNP epitaxial planar type

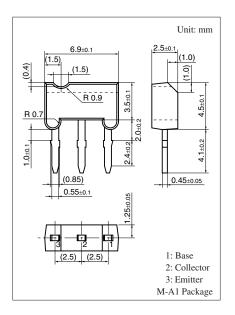
### For low-frequency output amplification

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | -25         | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | -20         | V    |  |
| Emitter-base voltage (Collector open) | $V_{EBO}$        | -7          | V    |  |
| Collector current                     | $I_C$            | - 0.5       | A    |  |
| Peak collector current                | $I_{CP}$         | -1          | A    |  |
| Collector power dissipation           | P <sub>C</sub>   | 600         | mW   |  |
| Junction temperature                  | $T_{j}$          | 150         | °C   |  |
| Storage temperature                   | $T_{stg}$        | -55 to +150 | °C   |  |



### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

| Parameter                                    | Symbol               | Conditions   | Min | Тур | Max   | Unit |
|--|----------------------|--|-----|-----|-------|------|
| Collector-base voltage (Emitter open)        | V <sub>CBO</sub>     | $I_C = -10 \ \mu A, I_E = 0$                                       | -25 |     |       | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>     | $I_C = -1 \text{ mA}, I_B = 0$                                     | -20 |     |       | V    |
| Emitter-base voltage (Collector open)        | V <sub>EBO</sub>     | $I_E = -10 \mu A, I_C = 0$   | -7  |     |       | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$            | $V_{CB} = -25 \text{ V}, I_E = 0$                                  |     |     | - 0.1 | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEO</sub>     | $V_{CE} = -20 \text{ V}, I_B = 0$                                  |     |     | -1    | μΑ   |
| Forward current transfer ratio *1            | h <sub>FE1</sub> *2  | $V_{CE} = -2 \text{ V}, I_{C} = -0.5 \text{ A}$                    | 90  |     | 220   | _    |
|  | h <sub>FE2</sub>     | $V_{CE} = -2 \text{ V}, I_{C} = -1 \text{ A}$                      | 25  |     |       | _    |
| Collector-emitter saturation voltage *1      | V <sub>CE(sat)</sub> | $I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$                      |     |     | - 0.4 | V    |
| Base-emitter saturation voltage *1           | V <sub>BE(sat)</sub> | $I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$                      |     |     | -1.2  | V    |
| Transition frequency                         | $f_T$                | $V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$ |     | 150 |       | MHz  |
| Collector output capacitance                 | C <sub>ob</sub>      | $V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$               |     | 15  | 25    | pF   |
| (Common base, input open circuited)          |                      |  |     |     |       |      |

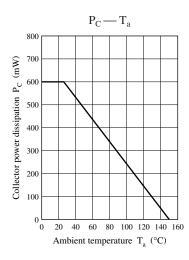
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

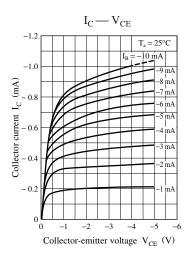
#### 2. \*1: Pulse measurement

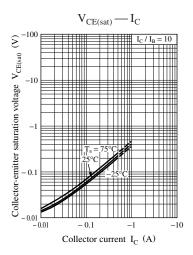
#### \*2: Rank classification

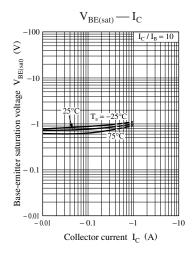
| Rank               | Q         | R          |
|--------------------|-----------|------------|
| $h_{\mathrm{FE1}}$ | 90 to 155 | 130 to 220 |

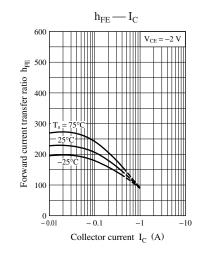
Note) The part number in the parenthesis shows conventional part number.

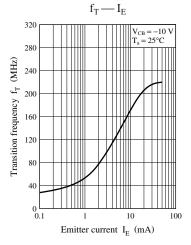


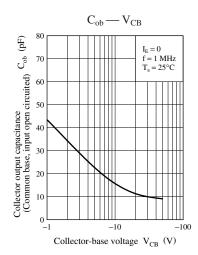












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